## Homework 5 - Joshua Gould - VLSI - Sec. 1

Tuesday, October 30, 2018 5:01 PM

You are synthesizing a chip composed of random logic with an average activity factor of 0.1. You are using a standard cell process with an average switching capacitance of 450 pF/mm<sup>2</sup>. Estimate the dynamic power consumption of your chip if it has an area of 70 mm<sup>2</sup> and runs at 450 MHz at  $V_{DD} = 0.9$  V.

$$\alpha = 0.1$$

$$\frac{C}{mm^2} = 450 \frac{pF}{mm^2}$$

$$A = 70 \text{ } mm^2$$

$$f = 450 \text{ } MHz$$

$$V_{DD} = 0.9 \text{ } V$$

$$P_{dym} = \alpha C V_{dd}^2 f = (0.1) * \left(\frac{450pF}{mm^2} * 70mm^2 *\right) (0.9^2) * (450,000,000) = 1.15 \text{ W}$$

## Example 5.4

Consider the system-on-chip from Example 5.1. Subthreshold leakage for OFF devices is 100 nA/μm for low-threshold devices and 10 nA/μm for high-threshold devices. Gate leakage is 5 nA/μm. Junction leakage is negligible. Memories use lowleakage devices everywhere. Logic uses low-leakage devices in all but 5% of the paths that are most critical for performance. Estimate the static power consumption.

$$I_{low} = \frac{100nA}{\mu m}$$
  $\lambda$ = 65 nm process  

$$Logic width = 12 \lambda$$
 Memory width = 4  $\lambda$   

$$Logic uses low in all but 5% Channel Lengths drawn = .025 \mu m$$

$$I_{gate} = \frac{5nA}{\mu m}$$
  $\#_{logic} = 50 \cdot 10^6$ 

$$\#_{mem} = 950 \cdot 10^6$$

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$$T_{highlog_{5\%}} = 50 * 10^{6} (0.05)(12\lambda) \left(\frac{0.025 \ \mu m}{\lambda}\right) = 0.75 * 10^{6} \mu m$$

$$T_{lowlog_{95\%}} = 50 * 10^6 (0.95)(12\lambda) + 950 * 10^6 (4\lambda)(\frac{0.025\mu m}{\lambda}) = 109.25 * 10^6 \mu m$$

$$I_{logsub} = 0.75 * 10^6 (100nA) + 109.25 * 10^6 (10nA)/2 = 584mA$$

$$I_{gate} = 0.75 * 10^6 \mu m * \frac{100 nA}{\mu m} \left( \frac{5 \frac{nA}{\mu m}}{2} \right) = 275 \text{mA}$$

$$P_{max} = 275 + 584 = 859 mA$$

$$P_{static} = 275 + 584 = 859mA$$

5.10 Design a header switch for a power gating circuit in a 65 nm process. Suppose the pMOS transistor has an ON resistance of about 2.5 k $\Omega \cdot \mu$ m. The block being gated has an ON current of 100 mA. How wide must the header transistor be to cause less than a 2% increase in delay?

$$\lambda = 65 \ nm \ {
m process}$$
  $I_{on}$  = 100 mA  $R_{on} = 2.5 \ k\Omega * \mu m$  Delay increase = 0.02 = 2%  $R = \frac{2.5}{0.065} = 38.46 \ k\Omega$   $R_{eff} = \frac{20mV}{100mA} = 0.2\Omega$ 

$$W = 2.5k\Omega * \mu m / 0.0002k\Omega = 12,500 \mu m = 12.5 mm$$